AMENDMENT TO THE SPECIFICATION

Please replace the paragraph beginning at page 2, line 16, with the following rewritten paragraph:

Therefore, it is important to [[mange]] <u>manage</u> the xenon flash lamps <u>to ameliorate or prevent the aforementioned drawbacks of the prior art. Presently, while</u> there has been no concept of control in relation to the xenon flash lamps emitting flash light by instantaneously discharging energy of capacitors storing charges <u>and lamp</u>. <u>Lamp</u> management itself has been extremely difficult, to result in a method therefor.

Indirect management [[of]] by periodically sampling and inspecting processed wafers has generally been frequently employed as a method of managing xenon flash lamps. More specifically, whether [[or not]] proper thermal processing has been performed is inspected by taking out about one processed wafer per several lots and measuring the sheet resistance of the surface thereof. Even if an abnormality is recognized as a result of the inspection [[in]] of this method, however, there is a high possibility that a large number of semiconductor wafers processed between the inspections also cause suffer from processing abnormality abnormalities. Thus, this method is risky.

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